



# SOT337-1

plastic shrink small outline package; 14 leads; body width 5.3 mm

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	D (double)
<b>Package type descriptive code</b>	SSOP14
<b>Package type industry code</b>	SSOP14
<b>Package style descriptive code</b>	SSOP (shrink small outline package)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	MO-150
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	19-2-2003

Table 1. Package summary

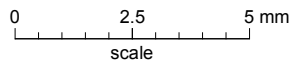
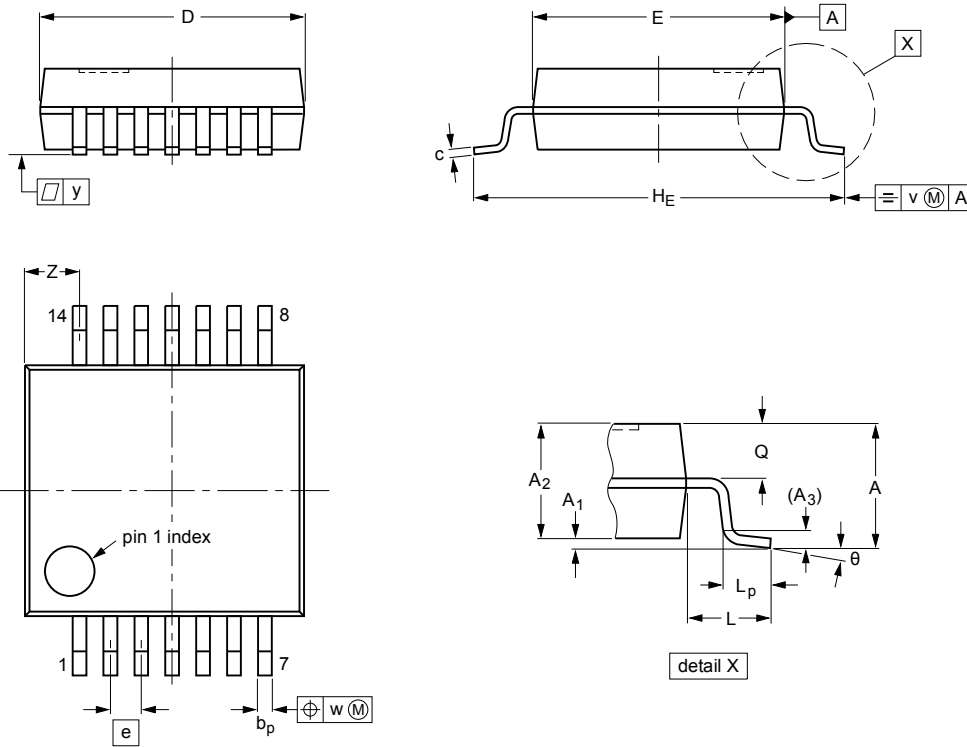
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	6	-	6.2	6.4	mm
E	package width	5.2	-	5.3	5.4	mm
A	seated height	[tbd]	-	2	2	mm
A <sub>2</sub>	package height	1.65	-	1.75	1.8	mm
n <sub>2</sub>	actual quantity of termination	-	-	14	-	



2. Package outline

SSOP14: plastic shrink small outline package; 14 leads; body width 5.3 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	e	H <sub>E</sub>	L	L <sub>p</sub>	Q	v	w	y	Z <sup>(1)</sup>	θ
mm	2	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	6.4 6.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	1.4 0.9	8° 0°

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

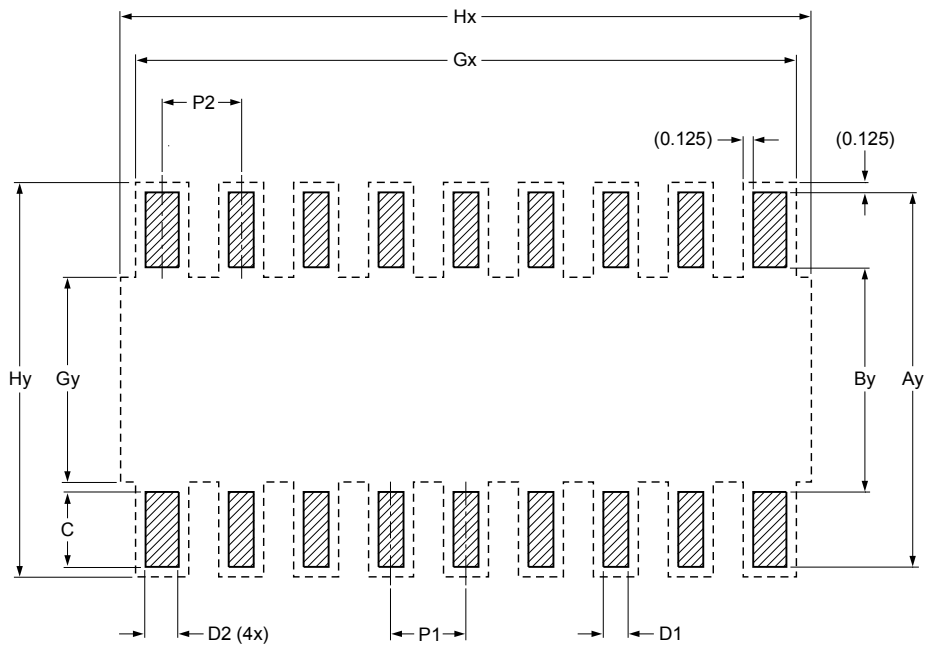
OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT337-1		MO-150			99-12-27 03-02-19

Fig. 1. Package outline SSOP14 (SOT337-1)


### 3. Soldering

Footprint information for reflow soldering of SSOP14 package

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Generic footprint pattern  
Refer to the package outline drawing for actual layout

 solder land  
- - - - occupied area

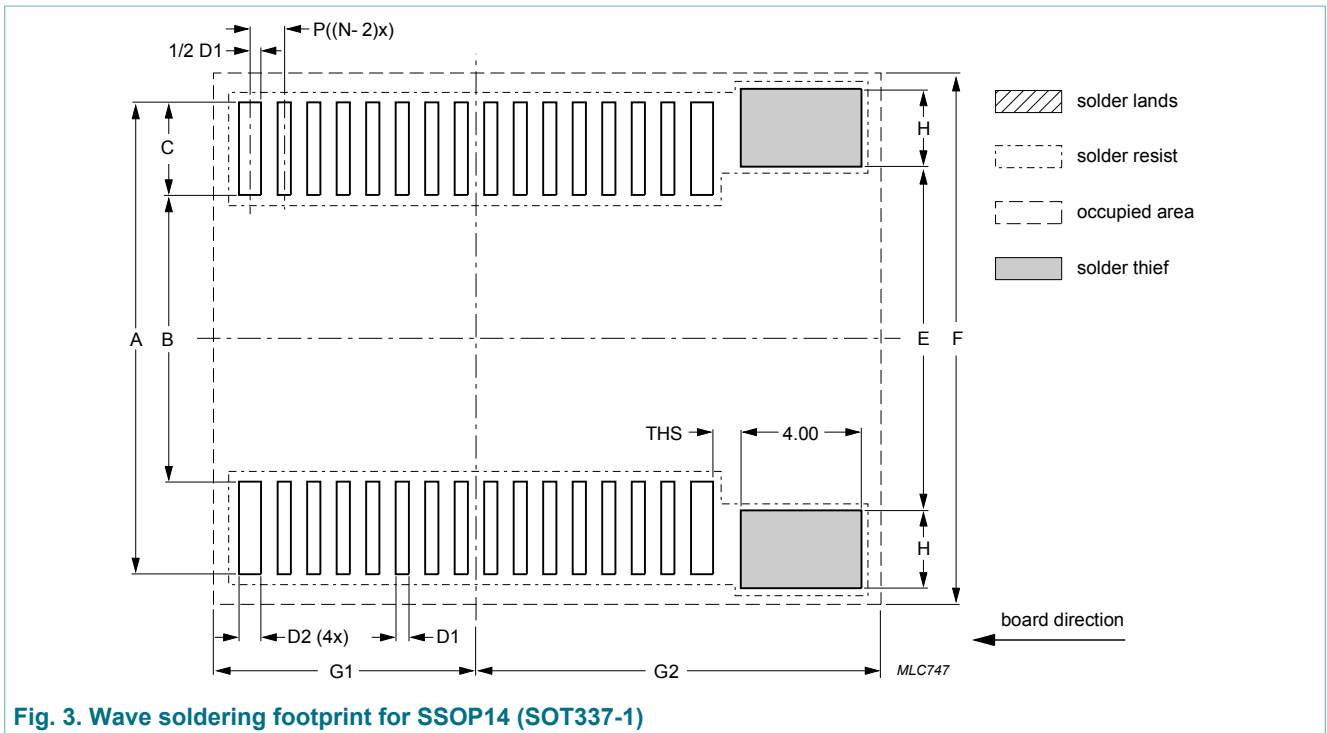
DIMENSIONS in mm

P1	P2	Ay	By	C	D1	D2	Gx	Gy	Hx	Hy
0.650	0.750	8.600	5.400	1.600	0.400	0.600	4.950	6.100	5.800	8.850

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Fig. 2. Reflow soldering footprint for SSOP14 (SOT337-1)

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## 4. Legal information

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